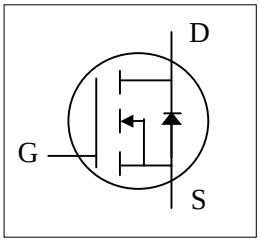
AP50T10GH/J-HF

Halogen-Free Product

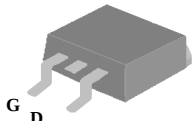
Advanced Power Electronics Corp.

N-CHANNEL ENHANCEMENT MODE POWER MOSFET

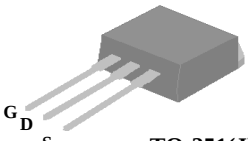
- ▼ **Simple Drive Requirement**
- ▼ **Lower Gate Charge**
- ▼ **Fast Switching Characteristic**
- ▼ **RoHS Compliant & Halogen-Free**



BV_{DSS}	100V
$R_{DS(ON)}$	30mΩ
I_D	37A



TO-252(H)



TO-251(J)

Description

AP50T10 series are from Advanced Power innovated design and silicon process technology to achieve the lowest possible on-resistance and fast switching performance. It provides the designer with an extreme efficient device for use in a wide range of power applications.

The TO-252 package is widely preferred for all commercial-industrial surface mount applications using infrared reflow technique and suited for high current application due to the low connection resistance. The through-hole version (AP50T10GJ) is available for low-profile applications.

Absolute Maximum Ratings@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
I_D@T_C=25℃	Continuous Drain Current, V_{GS} @ 10V	37	A
I_D@T_C=100℃	Continuous Drain Current, V_{GS} @ 10V	23	A
I_{DM}	Pulsed Drain Current[1]	120	A
P_D@T_C=25℃	Total Power Dissipation	89.2	W
P_D@T_A=25℃	Total Power Dissipation[3]	2	W
E_{AS}	Single Pulse Avalanche Energy[4]	60	mJ
I_{AR}	Avalanche Current[1]	20	A
E_{AR}	Repetitive Avalanche Energy[1]	8.9	mJ
T_{STG}	Storage Temperature Range	-55 to 150	℃
T_J	Operating Junction Temperature Range	-55 to 150	℃

Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Maximum Thermal Resistance, Junction-case	1.4	℃/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient (PCB mount)[3]	62.5	℃/W
Rthj-a	Maximum Thermal Resistance, Junction-ambient	110	℃/W

Electrical Characteristics@T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V, I_D=250uA	100	-	-	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=10V, I_D=24A	-	-	30	mΩ
		V_{GS}=5V, I_D=16A	-	-	70	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS}=V_{GS}, I_D=250uA	1	-	3	V
g_{fs}	Forward Transconductance	V_{DS}=10V, I_D=24A	-	30	-	S
I_{DSS}	Drain-Source Leakage Current	V_{DS}=80V, V_{GS}=0V	-	-	25	uA
I_{GSS}	Gate-Source Leakage	V_{GS}= ±20V, V_{DS}=0V	-	-	±100	nA
Q_g	Total Gate Charge	I_D=24A	-	42	67	nC
Q_{gs}	Gate-Source Charge	V_{DS}=80V	-	8	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	V_{GS}=10V	-	19	-	nC
$t_{d(on)}$	Turn-on Delay Time	V_{DS}=50V	-	11	-	ns
t_r	Rise Time	I_D=24A	-	42	-	ns
$t_{d(off)}$	Turn-off Delay Time	R_G=1Ω	-	26	-	ns
t_f	Fall Time	V_{GS}=10V	-	8.5	-	ns
C_{iss}	Input Capacitance	V_{GS}=0V	-	1840	2940	pF
C_{oss}	Output Capacitance	V_{DS}=25V	-	190	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	130	-	pF
R_g	Gate Resistance	f=1.0MHz	-	1.7	-	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage[2]	I_S=24A, V_{GS}=0V	-	-	1.3	V
t_{rr}	Reverse Recovery Time	I_S=10A, V_{GS}=0V	-	40	-	ns
Q_{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	80	-	nC

Notes:

1.Pulse width limited by Max. junction temperature.

2.Pulse test

3.Surface mounted on 1 in^2 copper pad of FR4 board

4.Starting T_j=25°C, V_{DD}=50V, L=0.3mH, R_G=25Ω, I_{AS}=20A.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

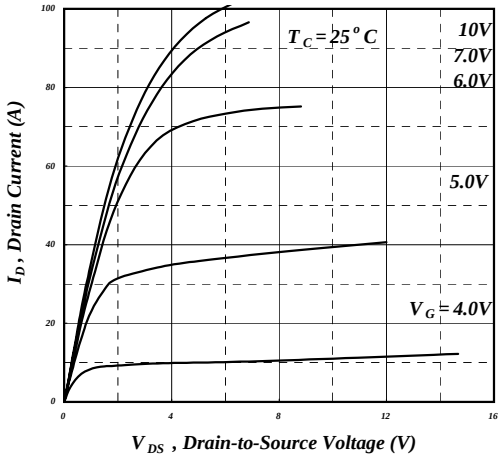


Fig 1. Typical Output Characteristics

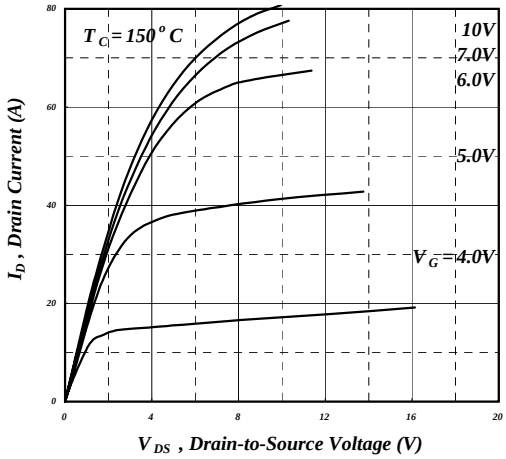


Fig 2. Typical Output Characteristics

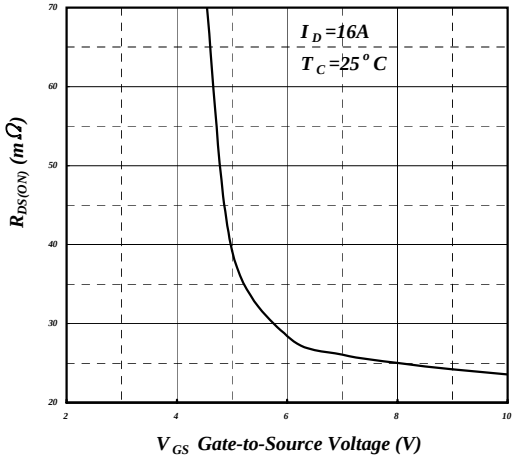


Fig 3. On-Resistance v.s. Gate Voltage

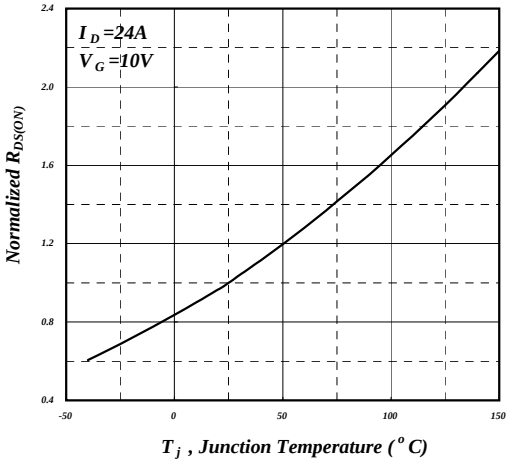


Fig 4. Normalized On-Resistance v.s. Junction Temperature

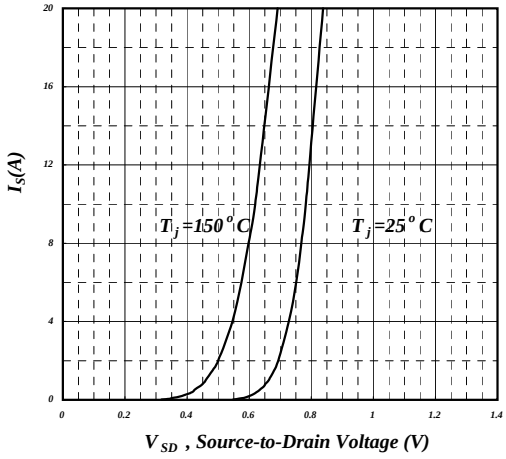


Fig 5. Forward Characteristic of Reverse Diode

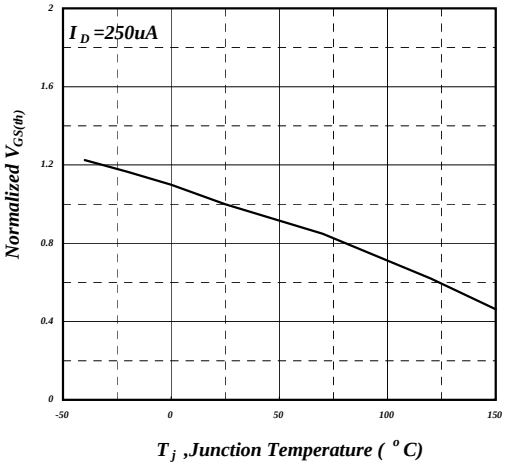


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

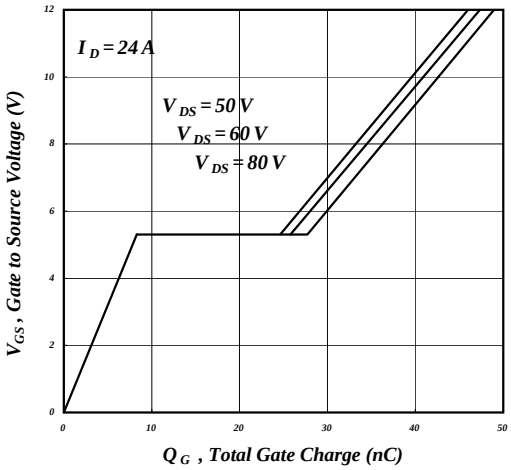


Fig 7. Gate Charge Characteristics

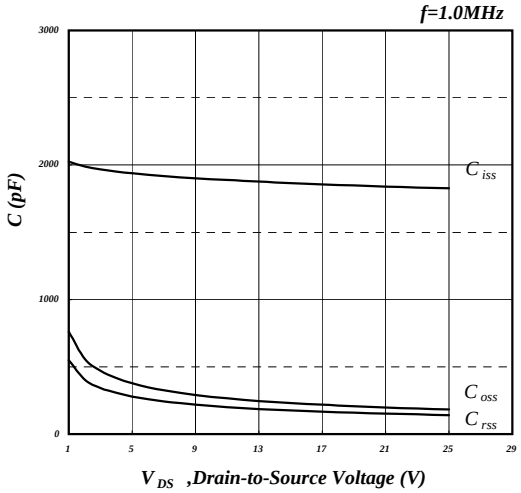


Fig 8. Typical Capacitance Characteristics

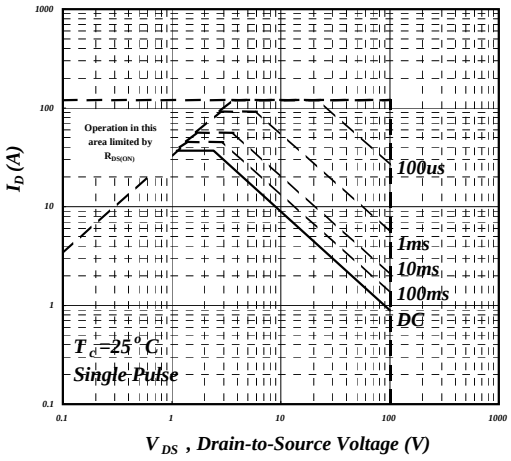


Fig 9. Maximum Safe Operating Area

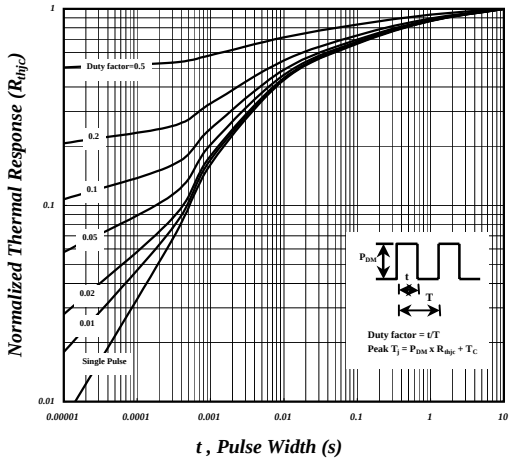


Fig 10. Effective Transient Thermal Impedance

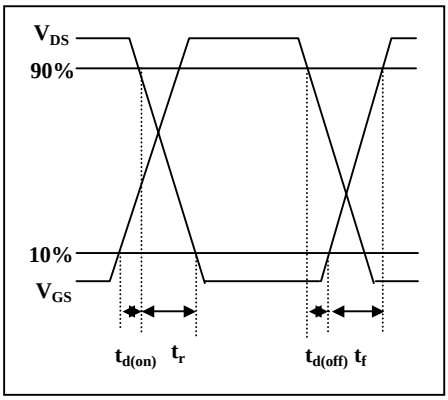


Fig 11. Switching Time Waveform

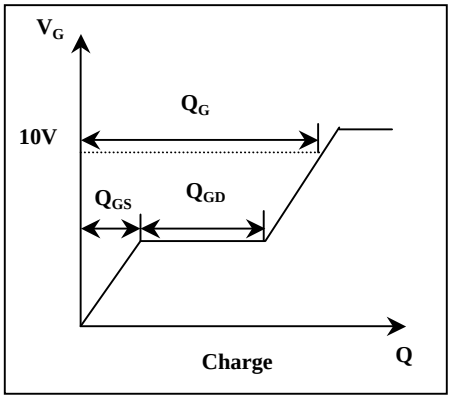
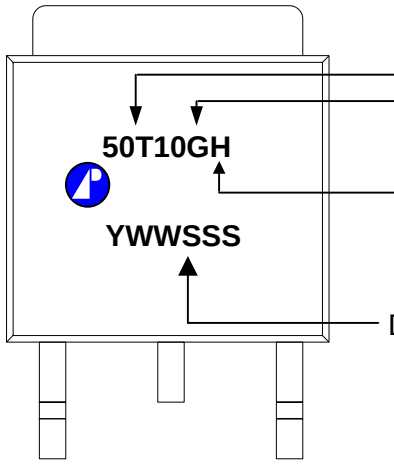


Fig 12. Gate Charge Waveform

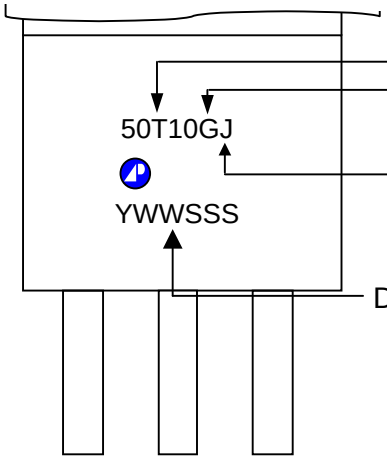
MARKING INFORMATION

TO-252



Part Number
meet Rohs requirement
for low voltage MOSFET only
Package Code
Date Code (YWWSSS)
Y：Last Digit Of The Year
WW：Week
SSS：Sequence

TO-251



Part Number
meet Rohs requirement
for low voltage MOSFET only
Package Code
Date Code (YWWSSS)
Y：Last Digit Of The Year
WW：Week
SSS：Sequence